



CY54/74FCT157T CY54/74FCT158T

Quad 2-Input Multiplexers

Features

- Function, pinout, and drive compatible with FCT and F logic
- FCT-C speed at 4.3 ns max. (Com'l), FCT-A speed at 5.0 ns max. (Com'l)
- Reduced V_{OH} (typically = 3.3V) versions of equivalent FCT functions
- Edge-rate control circuitry for significantly improved noise characteristics
- Power-off disable feature
- Matched rise and fall times
- Fully compatible with TTL input and output logic levels
- ESD > 2000V

- Sink current 64 mA (Com'l), 32 mA (Mil)
- Source current 32 mA (Com'l), 12 mA (Mil)

Functional Description

The FCT157T and FCT158T are quad two-input multiplexers that select four bits of data from two sources under the control of a common data Select input (S). The Enable input (\bar{E}) is Active LOW. When (\bar{E}) is HIGH, all of the outputs (Y) are forced LOW regardless of all other input conditions.

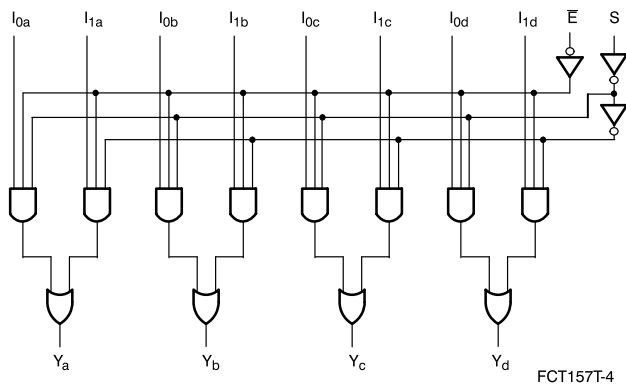
Moving data from two groups of registers to four common output buses is a common use of the FCT157T and FCT158T. The state of the Select input determines

the particular register from which the data comes. It can also be used as a function generator. The device is useful for implementing highly irregular logic by generating any four of the sixteen different functions of two variables with one variable common.

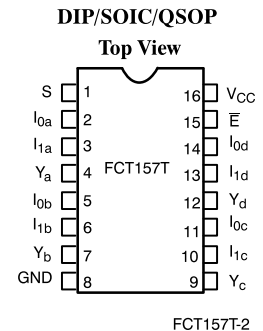
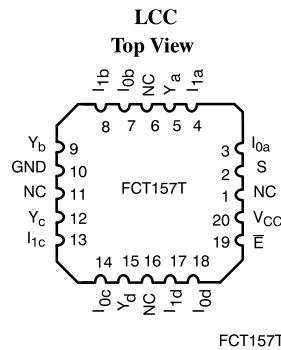
These devices are logic implementation of a four-pole, two-position switch where the position of the switch is determined by the logic levels supplied to the Select input. The outputs of the FCT157T are non-inverting whereas the FCT158T has inverting outputs.

The outputs are designed with a power-off disable feature to allow for live insertion of boards.

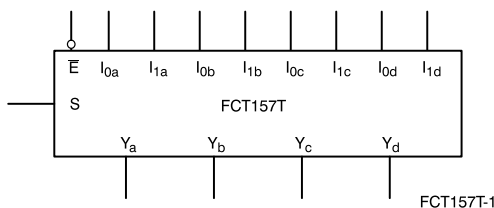
Logic Block Diagram, FCT157T

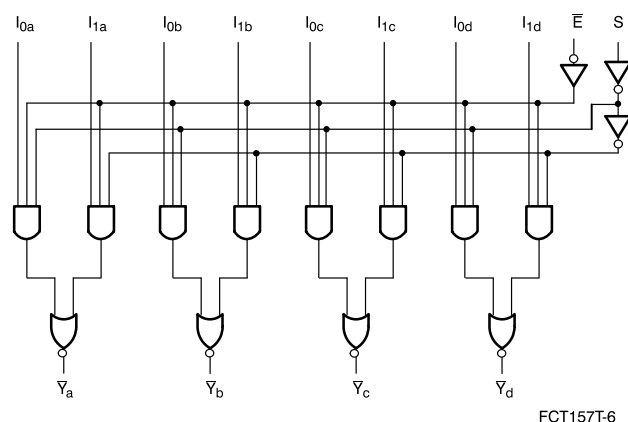
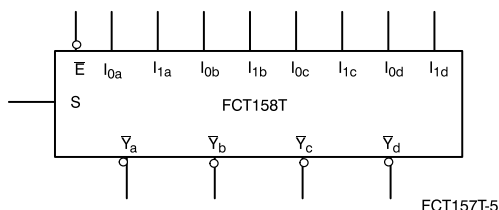
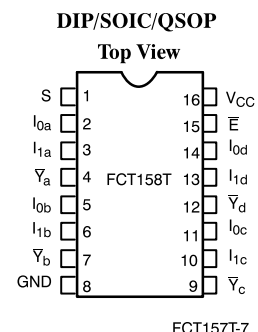
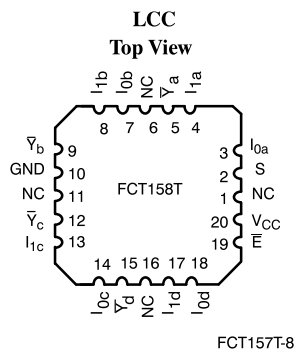


Pin Configurations



Logic Symbol



Logic Block Diagram, FCT158T

Logic Symbol

Pin Configurations

Pin Description

Name	Description
S	Common Select Input
\overline{E}	Enable Inputs (Active LOW)
I_0	Data Inputs from Source 0
I_1	Data Inputs from Source 1
Y	Non-Inverted Output (FCT157T)
\overline{Y}	Inverted Output (FCT158T)

Function Table^[1]—FCT157T

Inputs				Outputs
\overline{E}	S	I_0	I_1	Y
H	X	X	X	H
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

Function Table^[1]—FCT158T

Inputs				Outputs
\overline{E}	S	I_0	I_1	\overline{Y}
H	X	X	X	H
L	H	X	L	H
L	H	X	H	L
L	L	L	X	H
L	L	H	X	L

Note:

1. H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care.

Maximum Ratings^[2, 3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to $+150^{\circ}\text{C}$
 Ambient Temperature with
 Power Applied -65°C to $+135^{\circ}\text{C}$
 Supply Voltage to Ground Potential -0.5V to $+7.0\text{V}$
 DC Input Voltage -0.5V to $+7.0\text{V}$
 DC Output Voltage -0.5V to $+7.0\text{V}$
 DC Output Current (Maximum Sink Current/Pin) 120 mA
 Power Dissipation 0.5W

Static Discharge Voltage $>2001\text{V}$
 (per MIL-STD-883, Method 3015)

Operating Range

Range	Range	Ambient Temperature	V _{CC}
Commercial	CT	0°C to $+70^{\circ}\text{C}$	$5\text{V} \pm 5\%$
Commercial	T, AT	-40°C to $+85^{\circ}\text{C}$	$5\text{V} \pm 5\%$
Military ^[4]	All	-55°C to $+125^{\circ}\text{C}$	$5\text{V} \pm 10\%$

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		Min.	Typ. ^[5]	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} =Min., I _{OH} =-32 mA	Com'l	2.0			V
		V _{CC} =Min., I _{OH} =-15 mA	Com'l	2.4	3.3		V
		V _{CC} =Min., I _{OH} =-12 mA	Mil	2.4	3.3		V
V _{OL}	Output LOW Voltage	V _{CC} =Min., I _{OL} =64 mA	Com'l		0.3	0.55	V
		V _{CC} =Min., I _{OL} =32 mA	Mil		0.3	0.55	V
V _{IH}	Input HIGH Voltage			2.0			V
V _{IL}	Input LOW Voltage					0.8	V
V _H	Hysteresis ^[6]	All inputs			0.2		V
V _{IK}	Input Clamp Diode Voltage	V _{CC} =Min., I _{IN} =-18 mA			-0.7	-1.2	V
I _I	Input HIGH Current	V _{CC} =Max., V _{IN} =V _{CC}				5	μA
I _{IH}	Input HIGH Current	V _{CC} =Max., V _{IN} =2.7V				±1	μA
I _{IL}	Input LOW Current	V _{CC} =Max., V _{IN} =0.5V				±1	μA
I _{OZH}	Off State HIGH-Level Output Current	V _{CC} = Max., V _{OUT} = 2.7V				10	μA
I _{OZL}	Off State LOW-Level Output Current	V _{CC} = Max., V _{OUT} = 0.5V				-10	μA
I _{OS}	Output Short Circuit Current ^[7]	V _{CC} =Max., V _{OUT} =0.0V		-60	-120	-225	mA
I _{OFF}	Power-Off Disable	V _{CC} =0V, V _{OUT} =4.5V				±1	μA

Capacitance^[6]

Parameter	Description	Typ. ^[5]	Max.	Unit
C _{IN}	Input Capacitance	5	10	pF
C _{OUT}	Output Capacitance	9	12	pF

Notes:

- Unless otherwise noted, these limits are over the operating free-air temperature range.
- Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
- T_A is the "instant on" case temperature.
- Typical values are at V_{CC}=5.0V, T_A=+25°C ambient.
- This parameter is guaranteed but not tested.
- Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ. ^[5]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	$V_{CC} = \text{Max.}, V_{IN} \leq 0.2V,$ $V_{IN} \geq V_{CC} - 0.2V$	0.1	0.2	mA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs HIGH)	$V_{CC} = \text{Max.}, V_{IN} = 3.4V$ ^[8] $f_1 = 0$, Outputs Open	0.5	2.0	mA
I_{CCD}	Dynamic Power Supply Current ^[9]	$V_{CC} = \text{Max.}$, One Input Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE} = \text{GND}$, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$	0.06	0.12	mA/ MHz
I_C	Total Power Supply Current ^[10]	$V_{CC} = \text{Max.}$, 50% Duty Cycle, Outputs Open, One Input Toggling at $f_1 = 10 \text{ MHz}$, $\overline{OE} = \text{GND}$, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$	0.7	1.4	mA
		$V_{CC} = \text{Max.}$, 50% Duty Cycle, Outputs Open, One Input Toggling at $f_1 = 10 \text{ MHz}$, $\overline{OE} = \text{GND}$, $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$	1.0	2.4	mA
		$V_{CC} = \text{Max.}$, 50% Duty Cycle, Outputs Open, Four Bits Toggling at $f_1 = 2.5 \text{ MHz}$, $\overline{OE} = \text{GND}$, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$	0.7	1.4 ^[11]	mA
		$V_{CC} = \text{Max.}$, 50% Duty Cycle, Outputs Open, Four Bits Toggling at $f_1 = 2.5 \text{ MHz}$, $\overline{OE} = \text{GND}$, $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$	1.7	5.4 ^[11]	mA

Notes:

8. Per TTL driven input ($V_{IN} = 3.4V$); all other inputs at V_{CC} or GND.

9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.

10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_0/2 + f_1 N_1)$
 I_{CC} = Quiescent Current with CMOS input levels
 ΔI_{CC} = Power Supply Current for a TTL HIGH input ($V_{IN} = 3.4V$)
 D_H = Duty Cycle for TTL inputs HIGH

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamps and all frequencies are in megahertz.

11. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

Switching Characteristics Over the Operating Range

Parameter	Description	FCT157T				FCT157AT				Unit	Fig. No.[13]
		Military		Commercial		Military		Commercial			
		Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.		
t _{PLH} t _{PHL}	Propagation Delay I to Y	1.5	7.0	1.5	6.0	1.5	5.8	1.5	5.0	ns	1, 3
t _{PLH} t _{PHL}	Propagation Delay E to Y	1.5	12.0	1.5	10.5	1.5	7.4	1.5	6.0	ns	1, 5
t _{PLH} t _{PHL}	Propagation Delay S to Y	1.5	12.0	1.5	10.5	1.5	8.1	1.5	7.0	ns	1, 3

Parameter	Description	FCT157CT				Unit	Fig. No. ^[13]
		Military		Commercial			
		Min. ^[12]	Max.	Min. ^[12]	Max.		
t _{PLH} t _{PHL}	Propagation Delay I to Y	1.5	5.0	1.5	4.3	ns	1, 3
t _{PLH} t _{PHL}	Propagation Delay $\overline{\text{E}}$ to Y	1.5	5.9	1.5	4.8	ns	1, 5
t _{PLH} t _{PHL}	Propagation Delay S to Y	1.5	6.0	1.5	5.2	ns	1, 3

Switching Characteristics Over the Operating Range

Parameter	Description	FCT158T				FCT158AT				Unit	Fig. No. ^[13]
		Military		Commercial		Military		Commercial			
		Min. ^[12]	Max.	Min. ^[12]	Max.	Min. ^[12]	Max.	Min. ^[12]	Max.		
t _{PLH} t _{PHL}	Propagation Delay I to \bar{Y}	1.5	7.5	1.5	6.5	1.5	6.3	1.5	5.5	ns	1, 2
t _{PLH} t _{PHL}	Propagation Delay \bar{E} to \bar{Y}	1.5	12.5	1.5	11.0	1.5	7.9	1.5	6.5	ns	1, 5
t _{PLH} t _{PHL}	Propagation Delay S to \bar{Y}	1.5	12.5	1.5	11.0	1.5	8.6	1.5	7.5	ns	1, 2

Parameter	Description	FCT158CT				Unit	Fig. No. ^[13]
		Military		Commercial			
		Min. ^[12]	Max.	Min. ^[12]	Max.		
t _{PLH} t _{PHL}	Propagation Delay I to \overline{Y}	1.5	5.5	1.5	4.3	ns	1, 2
t _{PLH} t _{PHL}	Propagation Delay \overline{E} to \overline{Y}	1.5	6.4	1.5	4.8	ns	1, 5
t _{PLH} t _{PHL}	Propagation Delay S to \overline{Y}	1.5	6.5	1.5	5.2	ns	1, 2

Notes:

12. Minimum limits are guaranteed but not tested on Propagation Delays.
13. See "Parameter Measurement Information" in the General Information section.



Ordering Information—FCT157T

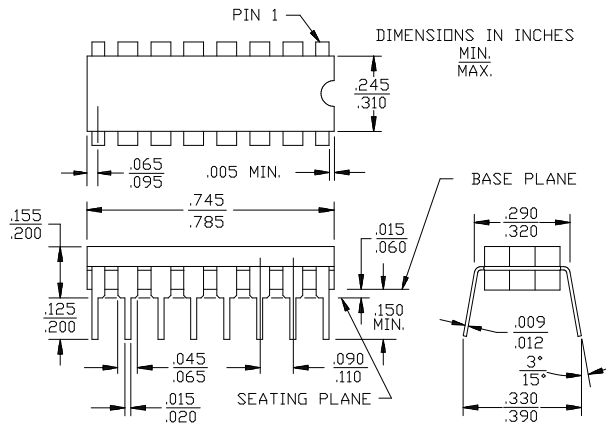
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.3	CY74FCT157CTPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT157CTQC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT157CTSOC	S1	16-Lead (300-Mil) Molded SOIC	
5.0	CY74FCT157ATPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT157ATQC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT157ATSOC	S1	16-Lead (300-Mil) Molded SOIC	
5.0	CY54FCT157CTDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT157CTLMB	L61	20-Pin Square Leadless Chip Carrier	
5.8	CY54FCT157ATDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT157ATLMB	L61	20-Pin Square Leadless Chip Carrier	
6.0	CY74FCT157TPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT157TQC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT157TSOC	S1	16-Lead (300-Mil) Molded SOIC	
7.0	CY54FCT157TDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT157TLMB	L61	20-Pin Square Leadless Chip Carrier	

Ordering Information—FCT158T

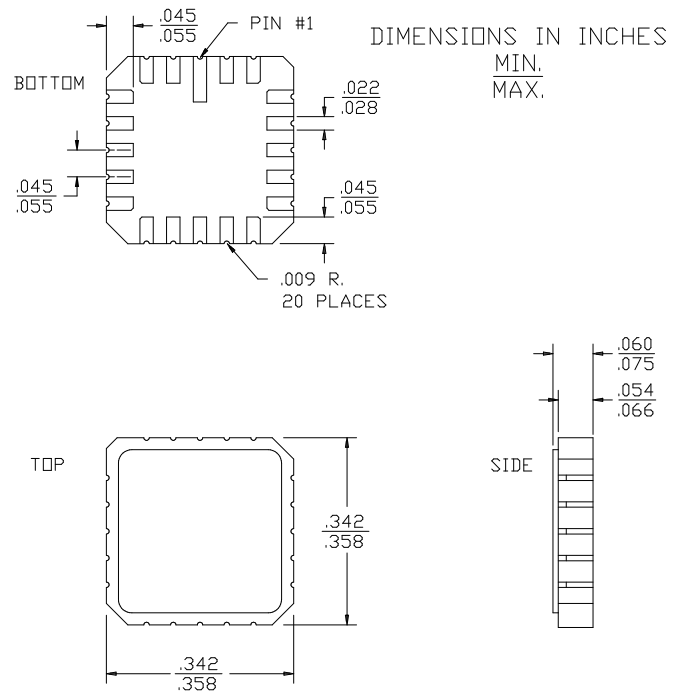
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.3	CY74FCT158CTPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT158CTQC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT158CTSOC	S1	16-Lead (300-Mil) Molded SOIC	
5.5	CY74FCT158ATPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT158ATQC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT158ATSOC	S1	16-Lead (300-Mil) Molded SOIC	
5.5	CY54FCT158CTDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT158CTLMB	L61	20-Pin Square Leadless Chip Carrier	
6.3	CY54FCT158ATDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT158ATLMB	L61	20-Pin Square Leadless Chip Carrier	
6.5	CY74FCT158TPC	P1	16-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT158TQC	Q1	16-Lead (150-Mil) QSOP	
	CY74FCT158TSOC	S1	16-Lead (300-Mil) Molded SOIC	
7.5	CY54FCT158TDMB	D2	16-Lead (300-Mil) CerDIP	Military
	CY54FCT158TLMB	L61	20-Pin Square Leadless Chip Carrier	

Package Diagrams

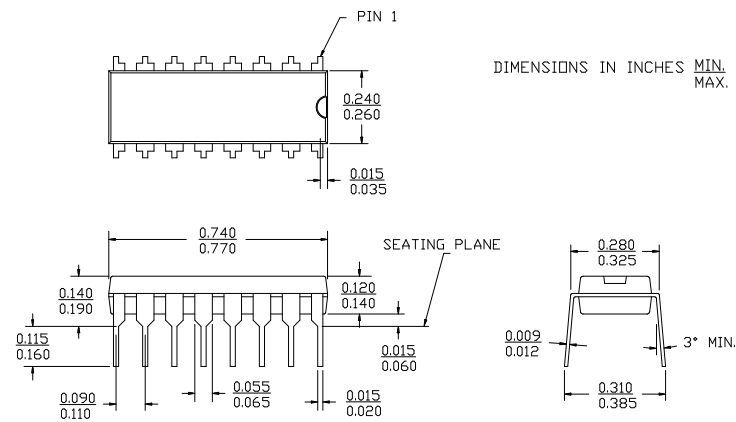
16-Lead (300-Mil) CerDIP D2
MIL-STD-1835 D-2 Config. A

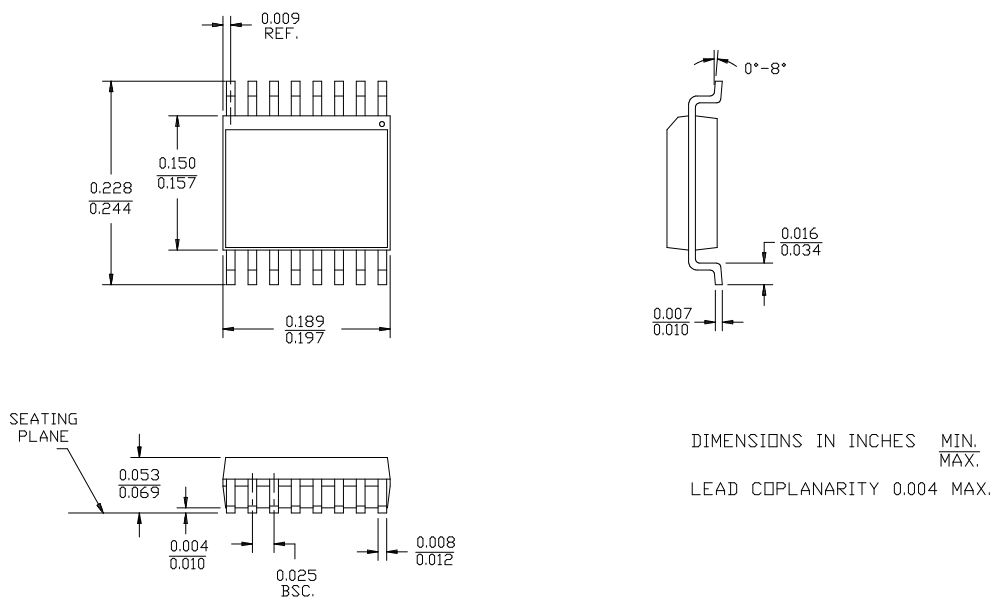


20-Pin Square Leadless Chip Carrier L61
MIL-STD-1835 C-2A



16-Lead (300-Mil) Molded DIP P1



Package Diagrams(continued)
16-Lead Quarter Size Outline Q1

16-Lead Molded SOIC S1
